Connect Tech
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CTai LABS
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Product Guide

CONNECTTECH.COM | CTAILABS.AI

Connect Tech

Our Place at the Edge

Dependable Platforms for Real-World Robotics

As robotics moves from the lab into real-world deployment, reliability at the Edge becomes critical. Connect Tech engineers and delivers platforms for robotics and Physical AI, that operate dependably, in real environments, simplifying Edge deployment, and enabling production-ready systems.

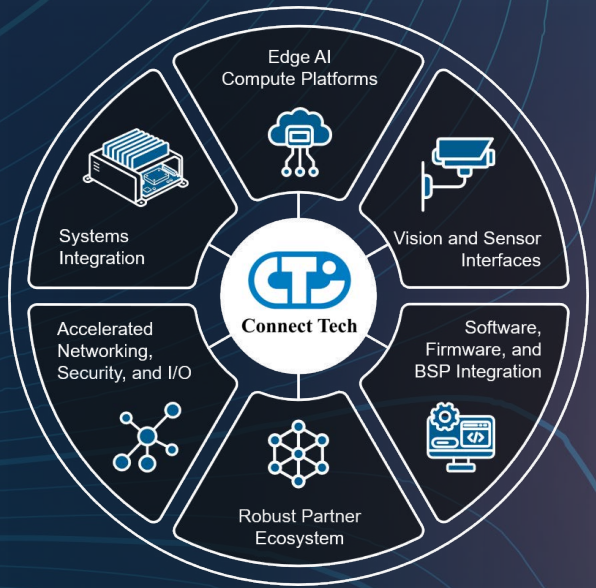
NVIDIA Elite Partner

"Everything that moves will be robotic someday, and it will be soon."
— Jensen Huang, CEO, NVIDIA

A Complete Edge AI Portfolio

Connect Tech provides the hardware, integration, and deployment foundation for production-ready Physical AI systems.

NVIDIA Elite Partner



Edge AI Compute Platforms

Edge AI compute performance spanning 1–10 TOPS to 100–300 TOPS to 2000+ TOPS, with power profiles from 5W to 130W+

End-to-End Deployable Solutions

Edge AI solutions adapt for systems in any environment and applications that require real-time reliable processing

Production Scale Integrated Solutions

From PoC to full-scale production, CTI solutions are customizable or off-the-shelf ready-for-scale

NOTE: Specifications found in this guide are subject to change without notice.

Our Focus Industries and Applications

Connect Tech

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Robotics and Logistics

Construction, Agriculture, and Mining

Aerospace and Defense

Industrial Automation

Smart Cities and Retail

Healthcare

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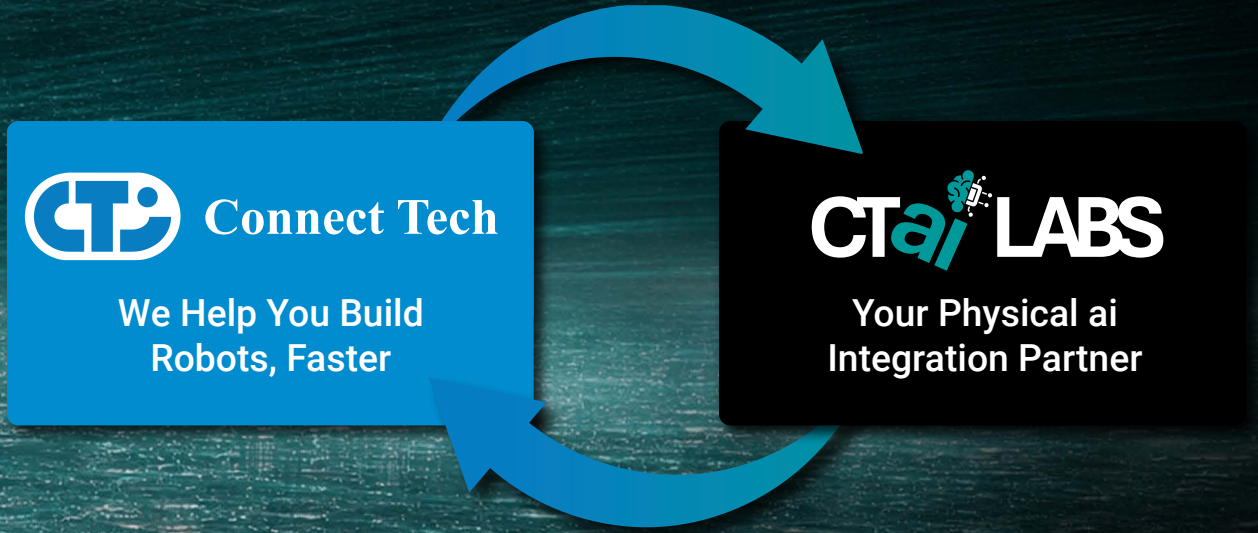
Your Physical ai Integration Partner

NVIDIA Elite Partner



Accelerating AI Robotics Deployment with CTI's EdgeAI Portfolio and Modular Ecosystem Integration Capabilities

CTai LABS Simplifies Physical ai So You Can Build Smarter, Faster

CTai LABS

Your Physical ai Integration Partner

Mission

Simplify Physical ai deployment so customers can build smarter, faster

What We Do

- Full-stack ai engineering for Edge platforms
- System and sensor integration
- Software bring-up and optimization
- Accelerate time-to-market for robotics and vision ai applications

Customer Benefit: Focus on building your product, not debugging integration issues

CTai LABS

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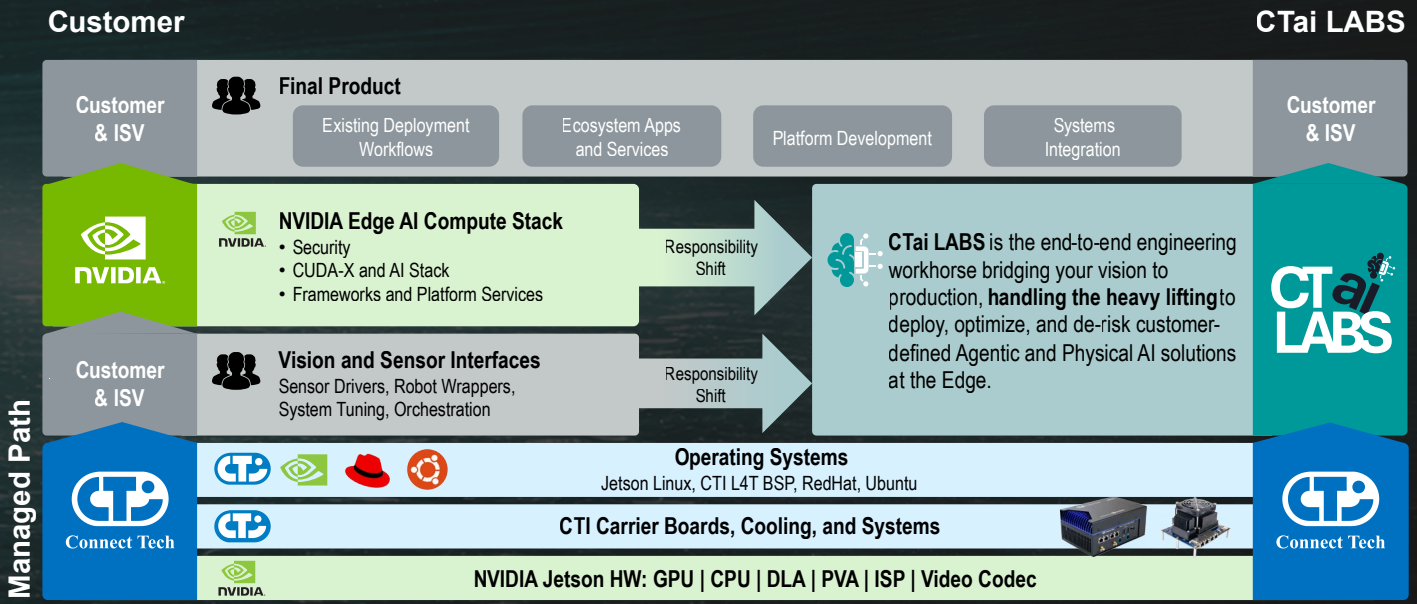
CTai LABS Solution Stack

From platform to deployment, CTai LABS handles the hard part, so you can build faster



NVIDIA Elite Partner

- 15 years of innovative partnership with the NVIDIA® Jetson™ Platform
- Expert Jetson infrastructure, hardware, BSP, sensor integration, and AI
- Customers benefit from accelerated time-to-market and direct collaboration

NVIDIA Elite Partner

Rugged, Validated Compute Platforms for Edge AI

Compute platforms built for Edge AI applications deliver flexible performance and form factors for deployment across a wide range of rugged environments.

10W–130W+ Performance
Scalable compute across deployment tiers

Multiple Processing Ecosystems
NVIDIA®, Intel®, AMD, TI, NXP, Qualcomm®

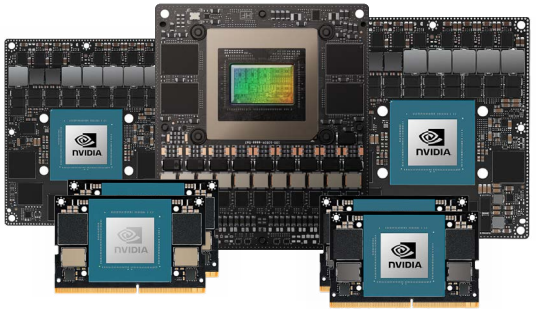
Production Ready
Long lifecycle and rugged deployment support

Jetson Orin™/ Thor™ Comparison Chart

-- Feature not available

	Orin Nano 4GB / 8GB	Orin NX 8GB / 16GB	AGX Orin 32GB	AGX Orin 64GB	AGX Orin Industrial	Jetson T4000	Jetson T5000	IGX T5000
AI Performance	20 TOPS / 40 TOPS	70 / 157 TOPS	200 TOPS	275 TOPS	248 TOPS	1200 TFLOPS (FP4-Sparse)	2070 TFLOPS (FP4—Sparse)	2070 TFLOPS (FP4—Sparse)
GPU	512/1024-core NVIDIA Ampere w/ 16 / 32 Tensor Core	512/1024-core NVIDIA Ampere w/ 16 / 32 Tensor Core	1792-core NVIDIA Ampere w/ 56 Tensor Cores	2048-core NVIDIA Ampere w/ 64 Tensor Cores	2048-core NVIDIA Ampere w/ 64 Tensor Cores	1536-core NVIDIA Blackwell w/ 64 5th-gen Tensor Cores; MIG	2560-core NVIDIA Blackwell w/ 96 5th gen Tensor Cores; MIG w/ 10 TPCs	2560-core NVIDIA Blackwell w/ 96 5th gen Tensor Cores; MIG w/ 10 TPCs
CPU	6-core Arm® Cortex® -A78AE v8.2 64-bit CPU	6-core Arm® Cortex® -A78AE v8.2 64-bit CPU	6-core Arm® Cortex® -A78AE v8.2 64-bit CPU	12-core Arm® Cortex® A78AE v8.2 64-bit CPU	12-core Arm® Cortex® A78AE v8.2 64-bit CPU	12-core Arm® Neoverse V3AE 64-bit CPU	14-core Arm® Neoverse V3AE 64-bit CPU	14-core Arm® Neoverse V3AE 64-bit CPU
Memory	4GB 64-bit / 8GB 128-bit LPDDR5 34 GB/s / 68 GB/s	8GB / 16GB 128-bit LPDDR5 102.4 GB/s	32GB 256-bit LPDDR5 204.8 GB/s	64GB 256-bit LPDDR5 204.8 GB/s	64GB 256-bit LPD-DR5 (+ECC) 204.8 GB/s	64 GB 256-bit LPDDR5X 273 GB/s	128GB 256 bit LPDDR5X 273 GB/s	128GB 256 bit LPDDR5X 273 GB/s
Storage	Supports External NVMe	Supports External NVMe	64GB eMMC 5.1	64GB eMMC 5.1	64GB eMMC 5.1	Supports external NVMe	Supports external NVMe	Supports external NVMe
Power	5W - 10W / 7W - 15W	10W | 15W | 20W | 40W	15W - 40W	15W - 60W	15W - 75W	40–70 W	40–130 W	40–130 W
PCIe	1 x4 + 3 x1 PCIe Gen3	3 x1 + 1 x4 PCIe Gen4	Up to 2 x8, 1 x4, 2 x1 (PCIe Gen4, Root Port & Endpoint)	Up to 2 x8, 1 x4, 2 x1 (PCIe Gen4, Root Port & Endpoint)	Up to 2 x8, 1 x4, 2 x1 (PCIe Gen4, Root Port & Endpoint)	Up to 8 lanes – Gen5	Up to 8 lanes – Gen5	Up to 8 lanes – Gen5
CSI Camera	Up to 4 cameras (8 via virtual channels)	Up to 4 cameras (8 via virtual channels)	Up to 6 cameras (16 via virtual channels)	Up to 6 cameras (16 via virtual channels)	Up to 6 cameras (16 via virtual channels)	Up to 6 cams through 16x lanes MIPI CSI-2 (virtual channels supported)	Up to 6 cams through 16x lanes MIPI CSI-2. Up to 32 cams using virtual channels	Up to 6 cams through 16x lanes MIPI CSI-2. Up to 32 cams using virtual channels
DL Accelerator	--	1x / 2x NVDLA v2.0	1x / 2x NVDLA v2.0	1x / 2x NVDLA v2.0	1x / 2x NVDLA v2.0	--	--	--
Vision Accelerator	--	1x PVA v2.0	1x PVA v2.0	1x PVA v2.0	1x PVA v2.0	1x PVA v3.0	1x PVA v3.0	1x PVA v3.0
Networking	1x 1GbE	1x 1GbE	1x 1GbE | 2x 10GbE	1x 1GbE | 2x 10GbE	1x 1GbE | 2x 10GbE	Up to 5GbE (system dependent)	4x 25GbE	4x 25GbE
Mechanical	69.6mm x 45mm 260-pin SO-DIMM connector	69.6mm x 45mm 260-pin SO-DIMM connector	100 mm x 87 mm, 699-pin Molex Mirror Mezz Connector	100 mm x 87 mm, 699-pin Molex Mirror Mezz Connector	100 mm x 87 mm, 699-pin Molex Mirror Mezz Connector	100 mm x 87 mm, 699-pin Molex Mirror Mezz Connector	100 mm x 87 mm, 699-pin Molex Mirror Mezz Connector	100 mm x 87 mm, 699-pin Molex Mirror Mezz Connector

NVIDIA® Jetson™ Product Lifecycle



NVIDIA Elite Partner

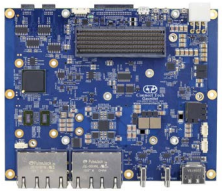
Jetson Module	Available Through
Jetson T4000	January 2036
Jetson T5000	August 2035
Jetson AGX Orin 64GB	January 2032
Jetson AGX Orin 32GB	January 2032
Jetson AGX Orin Industrial	July 2033

Jetson Module	Available Through
Jetson Orin NX 16GB	January 2032
Jetson Orin NX 8GB	January 2032
Jetson Orin Nano 8GB	January 2032
Jetson Orin Nano 4GB	January 2032

Product Change Notifications

Hardware component changes, with possible corresponding software changes, may occur during the product lifecycle (e.g. memory component updates). Scan the QR Code below to stay up-to-date with Connect Tech Product Change Notifications.

Jetson Thor™ Carrier Boards & Embedded Systems



Gauntlet

Gauntlet is a full-featured carrier board for NVIDIA® Jetson Thor™ modules, designed to deliver high-performance AI compute and scalable Edge deployments.

- 2x 10GbE + 2x 1GbE
- 16-Lane MIPI CSI-2 Camera Expansion
- Dual NVMe M.2
- M.2 B-Key (Cellular), M.2 E-Key (Wi-Fi), CAN, SPI, I2C, GPIO
- Operating Temperature: -40°C to +85°C (-40°F to +185°F)

AGX301

Rogue-T5

Rogue-T5 is a compact carrier board for NVIDIA® Jetson Thor™ designed for high-performance Edge AI and advanced vision systems.

- 2x 10GbE + 1x 2.5GbE
- 16-Lane MIPI CSI-2 Camera Expansion
- NVMe M.2
- CAN 2.0b, RS-232, I2C, GPIO, I2S
- Operating Temperature: -40°C to +85°C (-40°F to +185°F)

AGX302

Anvil-T5

Anvil-T5 is a rugged Edge AI system powered by NVIDIA® Jetson Thor™, engineered for robotics and autonomous platforms requiring high compute and multi-sensor integration.

- 2x 10GbE + 2x 1GbE
- GMSL3, GMSL2, FPD-Link III, SDI
- Dual NVMe M.2
- Rugged Multi-Vision I/O
- Operating Temperature: -25°C to +60°C (-13°F to +140°F)

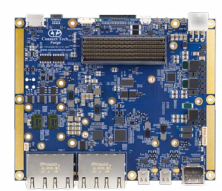
ESG625

Jetson Thor™ Platform Options

From compact carrier boards to rugged Edge AI systems, Connect Tech's Jetson Thor™ solutions are built to scale with your application. Whether deploying the Jetson T4000 for advanced Physical AI or the Jetson T5000 for maximum performance, CTI delivers the hardware foundation for next-generation robotics, vision, and autonomous systems.

Explore Connect Tech's Jetson Thor™ Solutions

Jetson AGX Orin™ Carrier Boards



Forge

Full-featured carrier board for the NVIDIA® Jetson AGX Orin™. This carrier board is specifically designed for commercially deployable platforms.

- 2x 10GbE, 2x 1GbE
- Up to 16 lanes MIPI CSI
- 2x NVMe M.2 M-Key, 1x M.2 B-Key, and 1x M.2 E-Key
- 2x USB 3.2, PCIe x4 OCuLink Connector
- Wide Input Power Range: +10V to 36V DC

AGX201

Rogue

Small Form Factor carrier board for the NVIDIA® Jetson AGX Orin™. Rogue for Orin is specifically designed for commercially deployable platforms, and has an extremely small footprint of 92 x 107mm.

- 2x 10GbE
- Extremely Small Form-Factor (Same size as AGX Orin module)
- 2x NVMe M.2 Key Slots
- 3x USB 3.2

AGX202

Rogue-RX

Rogue-RX is a full-featured carrier board specifically designed for rugged and harsh environments. Provides rugged positive locking high-speed connectors.

- Rugged Positive Locking Connectors
- 2x 10GbE
- Extremely Small Form-Factor (Same size as AGX Orin module)
- 2x NVMe M.2 Key Slots
- 3x USB 3.2

AGX203

Rogue-RX XP

Rogue-RX XP is a full-featured carrier board designed for rugged and harsh environments with extended wide-range power input and rugged positive-locking connectors.

- Rugged Positive Locking Connectors
- 2x 10GbE
- 2x NVMe M.2 Key Slots
- 3x USB 3.2 Gen2
- Wide Input Power Range: +10V to 36V DC

AGX207

Jetson AGX Orin™ Carrier Boards Comparison Chart

-- Feature not available

	Forge for AGX Orin	Rogue for AGX Orin	Rogue-RX for AGX Orin	Rogue-RX XP for AGX Orin
Part Number	AGX201	AGX202	AGX203	AGX207
Size	155mm x 126mm (6.10" x 4.96")	92mm x 107mm (3.62" x 4.21")	92mm x 108.2mm (3.62" x 4.26")	125mm x 108.7mm (4.92" x 4.28")
Compatibility	NVIDIA® Jetson AGX Orin™ 32GB, 64GB and Industrial	NVIDIA® Jetson AGX Orin™ 32GB, 64GB and Industrial	NVIDIA® Jetson AGX Orin™ 32GB, 64GB and Industrial	NVIDIA® Jetson AGX Orin™ 32GB, 64GB and Industrial
Ethernet	2x 10GbE Ports	2x 10GbE Ports	2x 10GbE Ports ix Industrial™ Rugged Positive Latching Connectors	2x 10GbE Ports ix Industrial™ Rugged Positive Latching Connectors
	2x 1GbE Ports	--	--	--
USB	1x USB 3.2 Ports (Type-C), 1x USB 3.2 Ports (Type-C - OTG Capable)	1x USB 3.2 Ports (Type-C – OTG Capable), 2x USB 3.2 Ports (Type-C)	2x USB 3.2 Gen2 10Gbps with Samtec AcceleRate® Rugged Positive Locking Connectors, 1x USB 3.2 Gen210Gbps (OTG Capable) Type-C	2x USB 3.2 Gen2 10Gbps with Samtec AcceleRate® Rugged Positive Locking Connectors, 1x USB 3.2 Gen210Gbps (OTG Capable) Type-C
Camera Inputs	1x 16-Lane MIPI Expansion Connector	1x 16-Lane MIPI Expansion Connector	1x 16-Lane MIPI Expansion Connector	1x 16-Lane MIPI Expansion Connector
	Add-on expansion boards are available for: 3G-SDI/HD-SDI, GMSL, FPD-Link III, HDMI Input and direct MIPI Input	Add-on expansion boards are available for: 3G-SDI/HD-SDI, GMSL, FPD-Link III, HDMI Input and direct MIPI Input	Add-on expansion boards are available for: 3G-SDI/HD-SDI, GMSL, FPD-Link III, HDMI Input and direct MIPI Input	Add-on expansion boards are available for: 3G-SDI/HD-SDI, GMSL, FPD-Link III, HDMI Input and direct MIPI Input
Storage	1x Micro SD, 2x M.2 Key M 2280 NVMe	1x Micro SD, 2x M.2 Key M 2280 NVMe	1x Micro SD, 2x M.2 Key M 2280 NVMe	1x Micro SD, 2x M.2 Key M 2280 NVMe
Misc. Interfaces	1x RS-232/485 UARTs	2x @3.3V Levels UART0 and UART1	2x @3.3V Levels UART0	2x @3.3V Levels UART0
	Micro USB Debug and 2x @3.3V Levels UARTs	Micro USB Debug UART	Micro USB Debug UART	Micro USB Debug UART
Power	+10 to 36V DC Wide Input Power D23	+12V DC Input Only	+12V DC Input Only	+10 to +36V DC Wide Input
	(6-Pin Mini-Fit Jr. Connector) Power D23	(Positive Locking Molex Mini-Fit Jr Header)	(Positive Locking Molex Mini-Fit Jr Header)	(6 pin Mini-Fit Jr Connector)
CAN	2x CAN 2.0b Non-Isolated Port	2x CAN 2.0b Non-Isolated Port	2x CAN 2.0b Non-Isolated Port	2x CAN 2.0b Non-Isolated Port
GPIO	4x 3.3V GPI Inputs	4x 3.3V GPIO (1x PWM Capable)	4x 3.3V GPIO (1x PWM Capable)	6x 3.3V level-shifted GPIO (1 PWM)
	6x 3.3V GPO Outputs (2x PWM Capable)	1x 3.3V Power Pin at 1A	1x 3.3V Power Pin at 1A	1x 3.3V Power Pin at 2A
	1x 3.3V Power Pin at 1A	--	--	--
Operating Temp.	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)

Jetson AGX Orin™ Embedded Systems

Sentry-X2

Designed for mission-critical applications in harsh environments, Sentry-X2 is a MIL-SPEC certified AI system built for computing at the tactical Edge.

- Pre-Integrated with NVIDIA® Jetson AGX Orin™ Industrial
- 2x Ethernet Ports: 10GbE, 2.5GbE
- 2x 3G-SDI / HD-SDI Inputs (ESG630 only)
- 2x 3G-SDI / HD-SDI Outputs (ESG630 only)
- Tested to IP67, MIL-STD-810H
- Up to 4TB Storage

ESG630/ESG633

Anvil-RX

Anvil-RX is a rugged IP67 Edge device powered by the NVIDIA® Jetson AGX Orin™ for mission-critical deployment in harsh environments.

- 2x 10GbE, 2x 2.5GbE
- 8x GMSL3 Camera Inputs
- Up to 4TB NVMe Storage with Multiple Expansion Options
- Rugged M12 Connectors
- Operating Temperature: -40°C to +65°C (-40°F to +149°F)

ESG635

Anvil

Built for compute-intensive AI applications, Anvil delivers a rugged and power-efficient platform for autonomous vehicles, smart cities, and vision systems.

- 2x 10GbE, 2x 1GbE
- 8x GMSL2, FPD-Link III or HD-SDI Camera Inputs (optional)
- 2x NVMe M.2 M-Key, 1x B-Key, 1x E-Key
- USB 3.2, External PCIe
- Wide Input Power Range: +10 to +36V DC

ESG620/ESG621

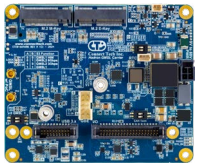
Inference Server

The AGX Orin™ Inference Server is a high-performance AI workstation powered by up to 12 NVIDIA® Jetson AGX Orin™ modules.

- Up to 275 TOPS per Module
- 2048-Core Ampere GPU + 64 Tensor Cores
- 4x 10G SFP+ Uplink Capabilities
- Up to 2TB NVMe Storage per Module
- 2U ATX-Style Redundant PSU

UAGX2U

Hadron Carrier Boards



Hadron GMSL

Boasting dual GMSL2 camera inputs. Hadron GMSL ensures high-speed, dependable data communication; crucial for autonomous applications.

- 2x USB 3.1, 1x 1GbE, 2x GMSL2 Coax Ports
- 1x NVMe M-Key, 1x M.2 E-Key
- 1x 1GbE with Rugged Positive Locking Pin Headers
- Wide Input Range: +9V to +60V DC

NGX018

Hadron MIPI

A compact solution for vision applications and unmanned payloads. With rugged latching connectors, it ensures secure connectivity in any environment.

- 2x USB 3.1, 1x 1GbE, 1x 2242/2230 NVMe, 1x M.2 E-Key (WiFi/BT)
- GPIO, PWM, I2C, RS-232, 3.3V UART, SPI
- Wide Input Range: +9V to +60V DC

NGX012/ NGX024

Super Hadron-DM

The Super Hadron-DM Carrier Board for Jetson Orin™ NX is an ultra-small, rugged, and feature-rich carrier for AI Computing at the Edge.

- Supports Super Mode
- 2x USB 3.1, 1x 1GbE, 1x 2242 NVMe, M.2 (M-Key)
- Dual 4-Lane MIPI CSI-2 22-Pin Connectors
- Wide Power Input: +10V to +60V DC

NGX027

	Hadron GMSL	Hadron MIPI	Super Hadron-DM
Part #	NGX018	NGX012/24	NGX027
Size	82.7mm x 68.8mm (3.25" x 2.71")	82.6mm x 58.8 mm (3.25" x 2.22")	87.6mm x 58.8mm (3.45" x 2.31")
Ethernet	1x 1GbE with Rugged Positive Locking Pin Headers	1x 1GbE with Rugged Positive Locking Pin Headers	1x 1GbE with Rugged Positive Locking Pin Headers
USB	2x USB 3.1 (Gen 1) (5 Gbps) with Rugged Positive Locking Pin Header	2x USB 3.1 (Gen 1)	2 x USB 3.1 (Gen 1)
Camera Inputs	2x GMSL2 Camera inputs w/ PoC	1x/2x 4-lane MIPI CSI-2 (22-pin connector)	2x 4-lane MIPI CSI-2 (22-pin FPC Connector)
Storage	1x 2242 NVMe (M-Key)	1x 2242/2230 NVMe (M-Key)	1x 2242/2230 NVMe (M-Key)
Misc. Interfaces	1x CAN 2.0b, 1x 3.3VTTL UART (CONSOLE), 2x RS-232 Serial Ports, 2x PWM capable, 4x GPIO, 1x 3.3V I2C	1x 3.3VTTL UART (CONSOLE), 2x RS-232 Serial Ports, 2x PWM capable, 4x GPIO, 1x 3.3V I2C, 1x 3.3V SPI	1x 3.3VTTL UART (CONSOLE), 2x RS-232 Serial Ports, 4x GPIO (I/O Header), 2x PWM Capable, 1x 3.3V I2C, 1x 3.3V SPI Power Output 3.3V, 5V (Max 500mA Each)
Power	+9V to +60V DC (+12V to +48V DC Nom.)	+9V to +60V DC (+12V to +48V DC Nom.)	+10V to +60V DC (+12V to +48V DC Nom.)
Weight	58g (2.05 oz)	49g (1.73 oz)	45g (1.59 oz)
Temp.	-25°C to +85°C (-13°F to +185°F)	-25°C to +85°C (-13°F to +185°F)	-25°C to +85°C (-13°F to +185°F)

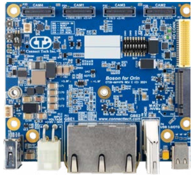
Boson Carrier Boards

Boson / Boson-22

A small, but powerful, vision-focused board for Jetson Orin™ NX. Packed with 4x PixelMate or 4x 22-Pin MIPI camera inputs, dual Gigabit Ethernet, USB C, and USB 3.0, all in a rugged and compact package.

- 2x 4-lane MIPI Modules, or 4x 2-lane MIPI Modules
- 2x 1GbE, USB 3.1 (USB C)
- NVMe for Additional Storage; WiFi and Bluetooth Expansion Options
- +9V to +36V DC Wide Input Voltage Range

NGX020/NGX021



Super Boson

The Super Boson introduces Orin Super Mode support to the Boson Carrier Family. Packed with 4x PixelMate camera inputs, dual Gigabit Ethernet, USB C, and USB 3.0, all in a rugged and compact package.

- 2x 4-lane MIPI Modules, or 4x 2-lane MIPI Modules
- 2x 1GbE, USB 3.1 (USB C)
- NVMe for Additional Storage; WiFi and Bluetooth Expansion Options
- +10V to +36V DC Wide Input Voltage Range

NGX028

	Boson	Boson-22	Super Boson
Part #	NGX020	NGX021	NGX028
Display	1x HDMI 2.0	1x HDMI 2.0	1x HDMI 2.0
Storage	1x M.2 M-Key (2280) NVMe PCIe x4 (Gen 3)	1x M.2 M-Key (2280) NVMe PCIe x4 (Gen 3)	1x M.2 M-Key (2280) NVMe PCIe x4 (Gen 3)
Expansion	1x 2230 E-Key Expansion for WiFi/Bluetooth 1x PCIe x1 + USB 2.0	1x 2230 E-Key Expansion for WiFi/Bluetooth 1x PCIe x1 + USB 2.0	1x 2230 E-Key Expansion for WiFi/Bluetooth 1x PCIe x1 + USB 2.0
Vision	PixelMate MIPI CSI x4 Connectors	22 Pin MIPI CSI x4 Connectors	PixelMate MIPI CSI x4 Connectors
USB	1x USB 3.1 Gen 2 w/ OTG capability (Type C) 1x USB 2.0 (Type A)	1x USB 3.1 Gen 2 w/ OTG capability (Type C) 1x USB 2.0 (Type A)	1x USB 3.1 Gen 2 w/ OTG capability (Type C) 1x USB 2.0 (Type A)
Power	+9V to +36V DC Input Voltage Range	+9V to +36V DC Input Voltage Range	+10V to 36V DC Input Voltage Range
Misc. Interfaces	3x 3.3V TTL UARTs (1x CONSOLE), 8 GPIOs 3.3V TTL (2x PWM Capable), 2x I2C 3.3V, 1x CAN 2.0b, 2x SPI, 2x 3.3V, 2x 5V, 8x GND	3x 3.3V TTL UARTs (1x CONSOLE), 8 GPIOs 3.3V TTL (2x PWM Capable), 2x I2C 3.3V, 1x CAN 2.0b, 2x SPI, 2x 3.3V, 2x 5V, 8x GND	3x 3.3V TTL UARTs (1x CONSOLE), 8 GPIOs 3.3V TTL (2x PWM Capable), 2x I2C 3.3V, 1x CAN 2.0b, 2x SPI, 2x 3.3V, 2x 5V, 8x GND
Operating Temp.	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)
Weight	80g (2.82oz)	80g (2.82oz)	80g (2.82oz)
Dimensions	90mm x 75mm (3.54” x 2.95”)	90mm x 75mm (3.54” x 2.95”)	90mm x 75mm (3.54” x 2.95”)

Embedded Systems

Sentry-X2 Mini

The Sentry-X2 Mini is a compact, rugged Edge AI system designed for aerospace and defense applications requiring secure, high-performance computing in constrained environments.

- NVIDIA® Jetson Orin™ NX
- 2x Ethernet: 1x 2.5GbE, 1x 1GbE
- Environmental: MIL-STD-810H, DO-160H, MIL-STD-461G, MIL-HDBK-704F, MIL-HDBK-831
- Flexible I/O: UART, CAN, GPIO
- Optional WiFi support

ESG650

Falcon

The Falcon Vehicle System is a compact, rugged Edge AI platform powered by NVIDIA® Jetson Orin™ NX, designed for vehicle and autonomous applications requiring reliable real-time processing.

- Jetson Orin NX (Super Mode)
- 4x GMSL2 Camera Inputs
- 2x 100/1000BASE-T1 + 1x 1GbE
- 2x CAN 2.0B/FD, 2x USB 2.0
- M.2 NVMe Storage
- +9V to +36V DC Input Power

ESG615

Polaris

Powered by the NVIDIA® Jetson Orin™ NX and designed for robotics, smart cities, and autonomous machines, the rugged Polaris system delivers extensive I/O in an IP67-rated enclosure.

- IP67-rated, Active or Passive Cooling
- 2x USB 3.1, 4x GMSL2 (sealed FAKRA), G/5G/LTE, Wi-Fi/BT, GNSS, M.2 2280 NVMe (M-Key)
- Rugged M12 I/O: 2x GbE, 2x CAN, GPIO, +18V to +48V DC Isolated Power

ESG604/ESG608

Essential EdgeAI

Low-cost network node, powered by NVIDIA® Jetson™, for scalable generative AI and AI-enabled video analytics.

- Boost Performance with Jetson Orin™ NX and Jetson Orin™ Nano Super Mode
- USB 3.1, GbE, and UART Connectivity
- Active or Passive Cooling Options
- Scalable AI Solution
- Compact Design

CORE01-07/03
CORE03-05

Connect Tech

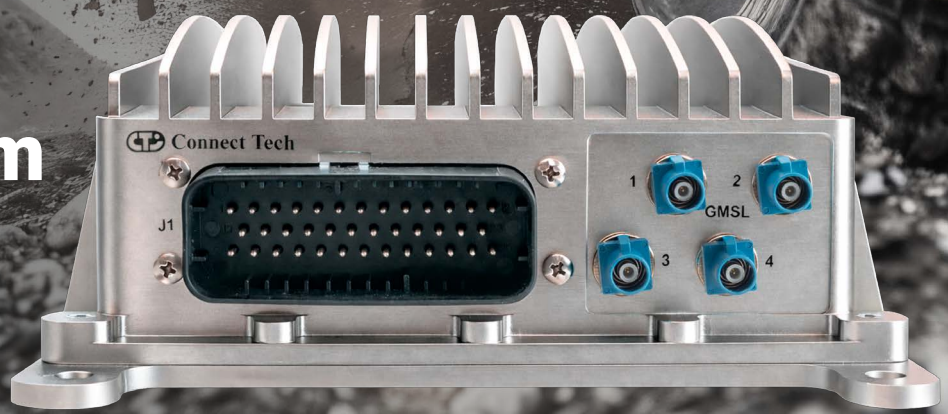
BEST IN SHOW AWARDS Embedded COMPUTING DESIGN embeddedworld WINNER

NVIDIA Elite Partner

IP67

Falcon
Vehicle System

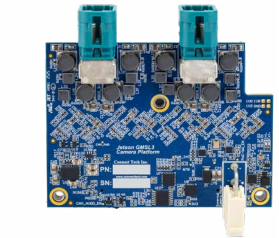
IP67 Jetson Orin™ NX Solution for Rugged Industrial Vehicles



Off-the-Shelf Integrations

- Camera (CSI / MIPI), LiDAR, Radar, IMU, GPS
- Industrial Vision: GMSL / SDI / FPD-Link III / USB / Ethernet
- Multi-sensor real-time integration, synchronization, and ingest

Camera Boards



GMSL3 Camera Platform

This expansion board supports up to 8 GMSL3 cameras connected to the Jetson AGX Orin™ and Jetson Thor™ module.

- 8x GMSL3 or GMSL2 Camera Inputs
- Power-Over-Coax, 4x Mini Coax Connector
- Internal or External Camera Power
- Allows Longer Length Cabling with a Direct Path to the Jetson AGX Orin ISP

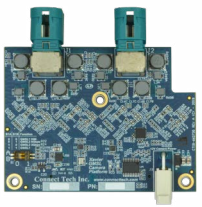
JCB009

GMSL2 Plus Camera Platform

Supports up to 8 GMSL2 cameras for NVIDIA® Jetson AGX Orin™ and Jetson Thor™ platforms using Power-over-Coax connectivity.

- 8x GMSL2 Camera Inputs
- 2x MATE-AX Quad Coax Connectors 16-lane MIPI CSI-2 Output
- Power-Over-Coax, Including Increased Front End Power Monitoring and Protection
- Internal or External Camera Power

JCB022



GMSL Camera Platform

This camera board supports up to 8x GMSL2 cameras to be connected to all AGX Orin™ Carrier Boards.

- Power-Over-Coax; Dual 4x Mini Coax Connector
- Internal or External Camera Power
- Allows Longer Length and Simplified Cabling with a Direct Path to the Jetson ISP

JCB002

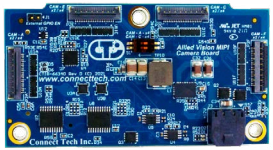
Camera Boards

SDI Vision Platform

Ultra-low latency SDI-to-MIPI CSI-2 conversion enables direct ISP ingest to NVIDIA® Jetson™ GPU compute.

- 2x 3G-SDI/HD-SDI/SDI (via 2x HD-BNC Connectors) Video Inputs
- 1x 3G-SDI/HD-SDI/SDI (via 1x HD-BNC Connector) Video Outputs
- PCBA Dimensions: 67mm x 75mm (2.64" x 2.95")
- PCBA, Height with Integrated Passive Heatsink: 17mm (0.67")

JCB003

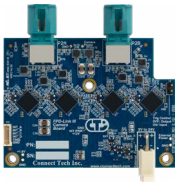


Allied Vision MIPI Camera Platform

This camera board enables direct connectivity for up to six MIPI sensors without additional hardware.

- Direct integration of Allied Vision MIPI CSI-2 Sensors with AGX Orin™
- Connect up to 6x 2-lane or 4x 4-lane MIPI Cameras
- Internal or External Camera Power

JCB005

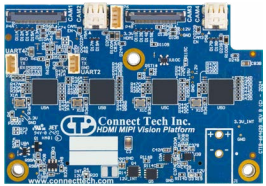


FPD-Link III Camera Platform

This expansion board connects FPD-Link III deserializers to AGX Orin™ carrier boards.

- 8x FPD-Link III Camera Inputs (2 per deserializer)
- 16-lane MIPI Output; Single 4-lane MIPI CSI-2 per Deserializer
- Internal or External Camera Power
- Power-Over-Coax

JCB006



HDMI Camera Platform

The HDMI Camera Platform enables direct HDMI video input with conversion to MIPI CSI-2 for NVIDIA® Jetson™ systems.

- 2x 30-pin KEL Connectors (Sony FCB Compliant)
- Dual Micro HDMI Inputs
- Supports up to 4 HDMI Inputs
- HDMI-to-CSI-2 Conversion for Vision Processing
- Powered Directly from Camera Expansion Header

JCB010

Camera Board Comparison Chart

-- Feature not available

	GMSL3 Camera Platform	GMSL2 Plus Camera Platform	GMSL Camera Platform	SDI Vision Platform	Allied Vision MIPI Camera Platform	FPD-Link III Camera Platform	HDMI Camera Platform
Part Number	JCB009	JCB022	JCB002	JCB003	JCB005	JCB006	JCB010
Size	75mm x 57mm (2.95" x 2.24")	75mm x 57mm (2.95" x 2.24")	75mm x 57mm (2.95" x 2.24")	75mm x 67mm (2.95" x 2.64")	75mm x 40.2mm (2.95" x 1.58")	75mm x 57mm (2.95" x 2.24")	75 mm x 52 mm (2.95" x 2.05")
Weight	45g (1.59 oz)	45g (1.59 oz)	50g (1.76 oz)	53g (1.86 oz)	19g (0.67 oz)	37g (1.3 oz)	23g (0.81 oz)
Connector	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.	1x High-Density Camera Board for the Camera Expansion Header on Rogue product line and Gauntlet.
Camera Inputs	8x Total (GMSL3/GMSL2)	8x Total (GMSL2)	8x Total (GMSL2/GMSL1)	2x 3G-SDI Inputs (HD-BNC)	Up to 6x MIPI CSI-2 (4x 4-lane or 6x 2-lane)	8x Total FPD-Link III	4x HDMI Inputs
Deserializer	Maxim MAX96792A	Maxim MAX9296A	Maxim MAX9296A	--	--	Texas Instruments DS90UB954	--
MIPI Output	2x 4-lane MIPI CSI-2 v1.3 output from each Deserializer (16-lanes total)	2x 4-lane MIPI CSI-2 v1.3 output from each Deserializer (16-lanes total)	2x 4-lane MIPI CSI-2 v1.3 output from each Deserializer (16-lanes total)	4-lane MIPI CSI-2 v1.3 output per SDI Input (8-lanes total)	4x 4-lane, or 6X 2-lane MIPI CSI-2	A single 4-lane MIPI CSI-2 v1.3 output from each Deserializer (16-lanes total)	A single 4-lane MIPI CSI-2 v1.01 output from each Bridge (16-lanes total)
Camera Input Connectors	2x MATE-AX Quad Coax Connectors Breakout cables to FAKRA available	2x MATE-AX Quad Coax Connectors Breakout cables to FAKRA available	2x MATE-AX Quad Coax Connectors Breakout cables to FAKRA available	2x Right Angle HD-BNC Connectors	6x MIPI CSI-2 connectors to interface to Allied Vision Alvium cameras	2x MATE-AX Quad Coax Connectors Breakout cables to FAKRA available	2x KEL USL00-30L 2x HDMI Type D (Micro HDMI)
Power	All 8 cameras will be sourced Power-Over-Coax from JCB009	All 8 cameras will be sourced Power-Over-Coax from JCB022	All 8 cameras will be sourced Power-Over-Coax from JCB002	Directly powered from Camera Expansion Header	Directly powered from Camera Expansion Header	All 8 cameras will be sourced Power-Over-Coax from JCB006	Directly powered from Camera Expansion Header
Operating Temp.	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	0°C to +85°C (32°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	-40°C to +85°C (-40°F to +185°F)	-30°C to +70°C (-22°F to +158°F)

ThermiQ™

Edge AI Cooling Solutions

by Connect Tech

NVIDIA® Jetson™ Cooling Solutions

AGX Orin™/Xavier Active Heat Sink

This active heat sink features a built-in fan for enhanced cooling, ensuring optimal performance and longevity of your NVIDIA® Jetson™ AGX module.

- Fits NVIDIA AGX Orin™ (Jetson AGX Xavier™ compatible)
- Active cooling with integrated fan
- Up to 60°C (140°F) ambient
- Dimensions: 100mm x 87mm x 54.5mm (3.94" x 3.43" x 2.15")
- Weight: 385.6g (0.85 lb)

XHG319

AGX Orin™/Xavier Passive Heat Sink

Efficiently dissipates heat from your NVIDIA® Jetson AGX Orin and AGX Xavier modules, ensuring optimal performance and longevity.

- Fits NVIDIA AGX Orin™ (Jetson AGX Xavier™ compatible)
- Passive convection cooling (requires airflow)
- Up to 60°C ambient (with airflow)
- Dimensions: 100mm x 87mm x 33.5mm (3.94" x 3.43" x 1.32")
- 294.8g (0.65 lb)

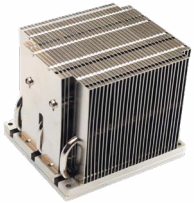
XHG320

Jetson Thor™ Active Heat Sink

Delivers active thermal management for the NVIDIA Jetson T5000 and T4000, maintaining consistent performance under sustained, high-load conditions.

- For Jetson T5000 & T4000 (AGX Orin™ compatible)
- Active cooling with integrated fan
- Up to 60°C (140°F) ambient
- Dimensions: 100mm x 87mm x 106mm (3.94" x 3.43" x 4.17")
- Weight: 688g (1.52 lb)

XHG332



Jetson Thor™ Passive Heat Sink

Provides efficient air-cooled thermal management for the NVIDIA Jetson T5000 and T4000.

- For Jetson T5000 & T4000 (AGX Orin™ compatible)
- Passive convection cooling (requires airflow)
- Up to 60°C (140°F) ambient
- Dimensions: 100mm x 87mm x 106mm (3.94" x 3.43" x 4.17")
- Weight: 629g (1.39 lb)

XHG333

NVIDIA® Jetson™ Cooling Solutions

Liquid Cooling Block

Superior thermal management, keeping your Jetson Thor™ or Jetson AGX Orin™ module cool under heavy loads for maximum performance.

- Fits Jetson Thor™ (Jetson AGX Orin™ compatible)
- Liquid cooling for high-performance operation
- Ambient temp dependent on coolant & system design
- Dimensions: 100mm x 87mm x 18mm (20.2mm w/ screws) (3.94" x 3.43" x 0.71" (0.8" w/ screws))
- Weight: 231g (8.15 oz)

XHG307

Active Heat Sinks

Jetson Orin NX/Nano
XHG325

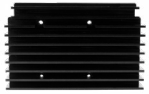
Jetson Xavier NX & Nano
XHG312, XHG314, XHG309

Jetson TX2-NX
XHG318

Passive Heat Sinks

Jetson Orin NX/Nano
XHG324

Jetson Xavier NX & Nano
XHG311, XHG308



Jetson TX2-NX
XHG317

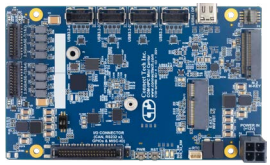
Thermal Plates

Jetson Orin NX/Nano
XHG323

Jetson Xavier NX & Nano
XHG313, XHG310

Jetson TX2-NX
XHG316

Carrier Boards

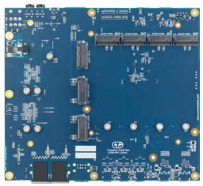


COM-HPC® Mini

Carrier board for the new COM-HPC® Mini specification, offering a wide range of connectivity with high-speed and ruggedized locking connectors

- COM-HPC Mini Compliant
- 4x USB 3.2
- 4x 2.5GbE
- 1x M-Key 2280 (NVMe)
- 1x USB 4/Display Port (Type C)
- 2x RS232, GPIO, I2C, CAN, SPI
- Dimensions: 115mm x 70mm (4.53" x 2.76")
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

HPC002



COM-HPC® Client

The COM-HPC Client Carrier Board is compatible with Size A, B, and C COM-HPC Client modules and features high-speed PC-style connectors and USB Type-C and Type-A connectors.

- For COM-HPC Client modules
- 2 x 2.5GbE
- 2 x USB 4 via USB Type-C
- 4 x 2280 M.2 M-Key, 2 x 3042 M.2 B-Key, 1x 2230 M.2 E-Key
- Dimensions: 200mm x 170mm (7.87" x 6.69")
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

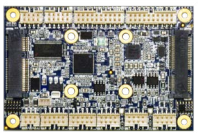
HPC003

Type 7

This Type 7 carrier board is ideal for high-compute, enterprise level applications needing access to high-end Intel® Xeon® D class processors.

- Supports Intel® Ice Lake Processors
- 2x 10GbE
- Ultra High Speed Storage with M.2 NVMe SSD Support
- Extremely Small Form Factor: 125mm x 95mm (4.92" x 3.74")
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

CCG101



Type 10 Mini

The Type 10 Mini carrier board is an extremely lite and small form factor carrier board featuring rugged, locking connectors and offers the ultimate in durability.

- Extremely Small Size: 84mm x 55mm (3.31" x 2.17")
- 2x USB 3.0, 4x USB 2.0
- 2 x mini PCIe, mSATA, 2x GbE, LVDS, Display Port HDMI/DVI/VGA, 2x RS 232/422/485

CCG020

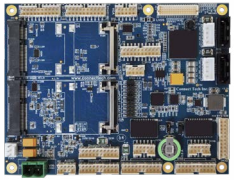
Carrier Boards

Type 6 104e

This is a compact carrier board matching the dimensions of a COM Express® Basic module and offers the ultimate durability with rugged, locking pin header connectors.

- PCIe/104 Type 1 (CCG018) or PCIe/104 Type 2 (CCG017)
- 4x USB 3.0, 2x 1GbE, 2x RS-232/485, LVDS (2×24), VGA
- On-Board Display Port/HDMI/DVI Display Switching
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

CCG017/CCG018

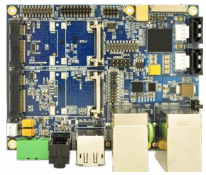


Type 6 Rugged Ultra Lite

The Type 6 Rugged Ultra Lite Carrier Board is compact. It offers the ultimate durability with locking, rugged pin headers. CCG011 supports only USB 2.0 and CCG012 supports USB 3.0.

- Mini-PCIe Expansion, USB 2.0, Display Port++
- Small Size, 95mm x 125mm (3.74" x 4.92")
- Supports Latest Intel® Processor Sets
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

CCG011/CCG012



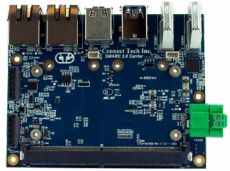
Type 6 Ultra Lite

The Type 6 Ultra Lite Carrier Board is a compact carrier board with standard PC connectors and is ideal for space constrained applications.

- COM Express® Type 6 Compatibility
- Mini-PCIe Expansion
- Supports Latest Intel® Processor Sets
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

CCG008

SMARC



SMARC 2.0 Carrier

Connect Tech's SMARC 2.0 carrier is an extremely small SMARC carrier board ideal for low-power IoT applications. Users can take advantage of the integrated on-board wireless capabilities.

- Feature Packed (HDMI, SATA, 2x MIPI CSI-2 Camera Interfaces)
- 2x USB 3.0, 2x USB 2.0, 2x USB 2.0 to miniPCIe
- Input Voltage +5V DC Only
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

SRG004

COM Express® Type 6 + GPU Embedded System

The COM Express Type 6 + GPU Embedded System combines High-End NVIDIA GPUs with latest generation x86 processors into a ruggedized small form factor embedded system.

- CPU: Intel Raptor Lake (13th Gen), Alder Lake (12th Gen), and Tiger Lake (11th Gen) Options Available
- GPUs Can be Targeted for Independent Display Outputs OR for a Headless GPU Processing System Utilizing CUDA® Cores

VXG SERIES

COM Express® Type 7 + GPU Embedded System

The COM Express Type 7 + GPU Embedded System combines 2x 10 GbE with Intel Xeon® D (Server Class) processors with high-end NVIDIA GPUs all into a small form factor embedded system.

- CPU: Intel Ice Lake D
- GPU: RTX3500 ADA, RTX5000 ADA
- GPUs Can be Targeted for Independent Display Outputs OR for a Headless GPU Processing System Utilizing CUDA® Cores

V7G SERIES

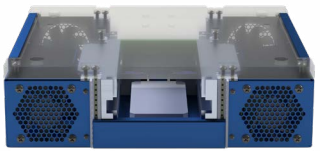
EdgeAQ Edge AI System

The EdgeAQ Edge AI System combines the Toradex Aquila TI AM69 with a compact, deployment-ready enclosure for high-performance vision and AI applications at the Edge.

- Ideal for Real-Time Vision Processing, Edge AI, and Machine Learning Applications
- AI Performance: Up to 32 TOPS
- 4x GMSL2 Camera Inputs with 2x 1GbE, 4x USB Type-A, and 1x USB Type-C
- Expansion: NVMe Storage with M.2 B-Key and E-Key Support
- Compact Enclosure: 136mm x 75mm x 109mm (5.35" x 2.95" x 4.29")

ESG202

VPX Chassis



Designed for rapid lab development and evaluation, this 3U VPX chassis provides a compact, SOSA-aligned platform with included RTM support and active cooling for reliable bench-top operation.

- 3U / 1-Slot SOSA Aligned VPX Chassis
- RTM for I/O Included
- For Rapid Lab Development
- Active Cooling with Variable Fan Control
- 110 - 265VAC PSU Included

VDC001

AGX Orin

Graphite VPX

Graphite VPX is a 3U VPX peripheral card bringing NVIDIA® Jetson AGX Orin™ Industrial to rugged embedded VPX and SOSA-aligned systems.

- 3U VPX, SOSA-Aligned
- NVIDIA® Jetson AGX Orin™ Industrial
- PCIe x8 Gen4 (Endpoint or Host)
- Dual 10GBASE-KR Ethernet
- Industrial NVMe (1TB / 2TB)
- USB 3.2, Display Port, 1GbE, GPIO, UART

VPG004

GPU

Graphite VPX/GPU

Graphite VPX/GPU is a VITA 65-compliant 3U VPX peripheral card bringing NVIDIA® RTX A2000 ADA and RTX A1000 GPUs to rugged embedded VPX systems. The Graphite VPX/GPU supports up to four Display Port outputs or two DVI outputs.

- 3U VPX SOSA Aligned
- GPU Options: NVIDIA® RTX A2000 ADA NVIDIA® RTX A1000 ADA
- PCIe 3.0 (x8 or two x4) Data Plane Only
- VITA 46, 48, and 65 Compliant

VPG305

10GbE

Graphite VPX/10GbE

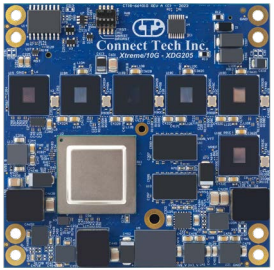
Rugged 10GbE managed Ethernet switch designed for demanding embedded applications and extreme temperature environments.

- 3U VPX SOSA-Aligned 10G / 2.5G / 1G Ethernet Switch
- 6x PCIe Gen 4 Ports (x4 each)
- Fully-Managed L2 / L3 Switching
- 7x 10G BASE-KR Ethernet
- 2x 10G SFP+ Ports
- -40°C to +85°C (-40°F to +185°F)

VPG205

10GbE

Xtreme/10G Managed Ethernet Switch /Router



Xtreme/10G Managed Ethernet Switch/Router provides high density, high port count Layer 2 switching, and Layer 3 routing with 10G uplinks. A total of 36 switchable ports, with 12x 10G/5G/2.5G and 24x 2.5G/1GbE copper ports in an extremely small form factor of 85mm x 85mm (3.35" x 3.35").

TSN feature set (802.1AS) supported through SFP interfaces.

- 36 Switchable Ports (12x10G/5G/2.5G/1GbE; 24x 2.5G/1GbE)
- High-Density Board-to-Board Connector
- Drop-in Replacement to Previous Generation Module (XDG201/XDG202)
- +4V to 14V Input Range
- Measurements: 85mm x 85mm (3.35" x 3.35")
- Extended Temperature Range -40°C to +85°C (-40°F to +185°F)

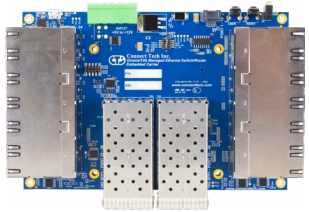
XDG205

Software Packages for Managed Ethernet Switches

Connect Tech's software design team builds support for our line of managed Ethernet switches using industry-leading firmware.

IStaX

Breakout Board



Xtreme/10G Managed Ethernet Switch/Router Embedded Carrier

- Improved RJ-45 Magnetics: Supporting 24x 2.5G/1G Copper Ports
- 8x 10G SFP+ ports (compared to 4x 10G and 4x 1G on XBG301)
- Improved USB and Serial Connectors
- Legacy Support for XDG201
- Improved 3.3V Power Supply to Support Higher Power Demand

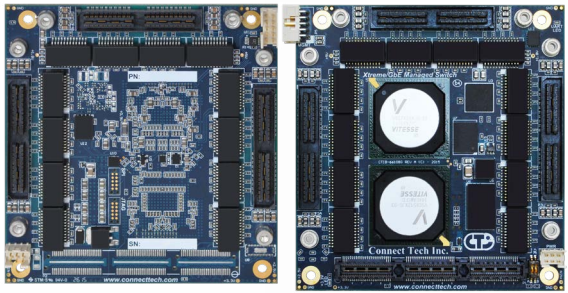
XBG305

I/O

Connect Tech has a wide range of product accessories including cables, antennas, power supplies, WiFi modules, 5G & LTE modules, frame grabbers, storage, and radio and Bluetooth modules. These complimentary products ensure full connectivity to our carriers and systems.

1GbE

Xtreme/GbE 24-Port Managed Carrier Ethernet Switch

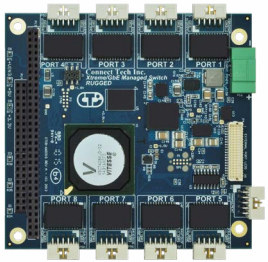


Xtreme/GbE 24-Port Managed Carrier Ethernet Switch provides high-density, high-port count, carrier-grade Ethernet switching capabilities in an extremely small embedded form factor. Excellent for any space constrained, mission-critical application needing an embedded high-density/high-port count managed Ethernet Switch.

The XDG025 is designed for standalone applications, with all thermal extraction on one layer and connector / cabling on the opposite layer.

- 24 Port GbE (10/100/1000 Mbps) Switch
- All 24 Port Magnetics Integrated On-Board
- High-Density Ruggedized Board-to-Board/Board-to-Cable Port Breakout
- Extremely Small Footprint 90mm x 96mm (3.55" x 3.78")
- Conduction Cooled Heatplate or Air Cooled Heatsink Options
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

XDG024/XDG025



Xtreme/GbE Managed Carrier Ethernet Switch

This 8 or 12 port Ethernet Switch is available with either standard RJ45 or rugged latching connectors with conduction cooled heatplates.

- 8 or 12 Port 10/100/1000 Mbps Switch
- Carrier Grade Ethernet Switching
- Available with RJ-45 or Rugged Locking Connectors
- Conduction Cooled Heatplate or Air Cooled
- 115.57mm x 111.58mm (4.55" x 4.39")
- Extended Temperature Range: -40°C to +85°C (-40°F to +185°F)

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- Reduced bring-up time and lower engineering overhead
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Tested to operate reliably in harsh conditions including shock, vibration, and extreme environments.

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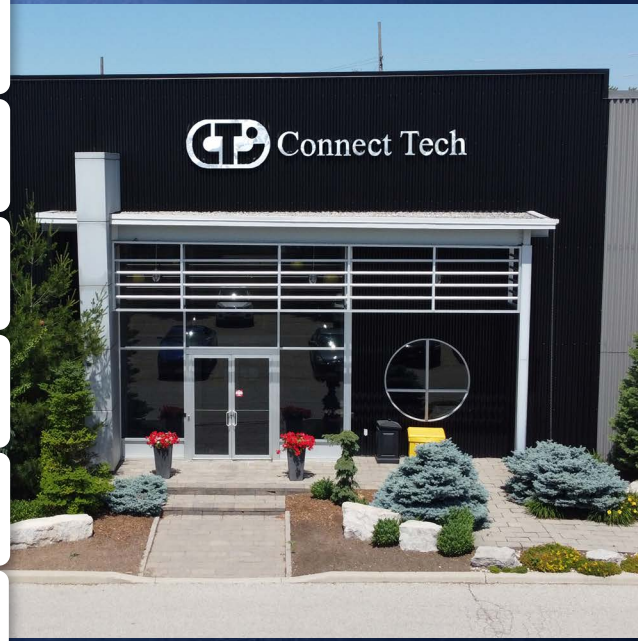

Established 1985 | Guelph, Ontario, Canada

From COTS to Custom

Flexible Edge AI Platforms
Designed for Rugged Deployment

Connect Tech

Scale From COTS to Fully Custom Edge AI Solutions, Faster

A Message From the President

For over 40 years, we've built integrated platforms for the engineers and teams working at the edge of what's possible. Our story began in 1985 in Guelph, Canada, co-founded by Engineer and Entrepreneur David J. Worthen, P.Eng., whose vision was to build technology that performs reliably in the most demanding real-world environments. That founding principle has remained at the core of who we are for 40+ years, guiding our evolution into a global leader in Edge AI computing for robotics, autonomous systems, and mission-critical applications.

With decades of in-house design and manufacturing experience, we've built integrated platforms that unify compute, vision, networking, and systems engineering to help you deploy faster and with confidence. As an NVIDIA Elite Partner, our team of experts has amassed 15+ years of innovation with the Jetson Platform. Through our newly introduced department, CTai LABS, we're now extending expertise into scalable Physical AI solutions.

Since joining HEICO Corporation in 2020, we've gained the support of a global aerospace and electronics leader while maintaining the agility and customer-first focus that defined our early years. This partnership further strengthens our ability to deliver purpose-built technology you can depend on.

At Connect Tech, we've spent four decades refining what it means to build hardware that truly performs and we're just getting started.

Sincerely,

Patrick Dietrich, P.Eng. | President, Connect Tech Inc.

Patrick Dietrich, P.Eng.
President, Connect Tech Inc.

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A HEICO COMPANY

Connect Tech

CTai LABS

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